

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
1	BRS	500	((integrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) with test\$3 with (head\$3 or probe\$1) with (switch\$3 or select\$3)	USPAT; US-PGPUB; EPO; 2004/03/10 JPO; DERWENT; IBM_TDB	2004/03/10 12:19		
2	BRS	1	((integrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and (test\$3 or measur\$3) with silicon with band with gap with voltage and capacit\$4	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 14:50		
3	BRS	602	702/68,81,82,83,84.ccls.	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 14:22		
4	BRS	1111	702/68,81,82,83,84,117.ccls.	USPAT; US-PGPUB; EPO; 2004/03/10 JPO; DERWENT; IBM_TDB	2004/03/10 12:26		
5	BRS	1868	702/68,81,82,83,84,117,118,120,121,122,123,124.ccls.	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 14:23		

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
6	BRS	1195	324/73.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 14:23		
7	BRS	4448	438/14,17.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 14:23		
8	BRS	9235	324/73.1,538,548,754,755,7 56,759,761,765.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 14:23		
9	BRS	0	((integrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) with test\$3 and memory with predetermined with distance\$1 with temperature\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 12:23		
10	BRS	1	((integrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) with test\$3 and memory with distance\$1 with temperature\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 12:27		

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
11	BRS	709	702/68,81,82,83,84.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 12:25		
12	BRS	1305	702/68,81,82,83,84,117.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 12:26		
13	BRS	2160	702/68,81,82,83,84,117,118,120,121,122,123,124.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 12:26		
14	BRS	1215	324/73.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 12:26		
15	BRS	4766	438/14,17.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 12:26		
16	BRS	9788	324/73.1,538,548,754,755,756,759,761,765.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 12:26		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
17 BRS	13	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) with test\$3 and pad\$1 with distance\$1 with temperature\$1	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 14:56		
18 BRS	719	702/68,81,82,83,84.ccls.	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 14:22		
19 BRS	2190	702/68,81,82,83,84,117,118,120,121,122,123,124.ccls.	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 14:23		
20 BRS	1216	324/73.1.ccls.	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 14:23		
21 BRS	4794	438/14,17.ccls.	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 14:23		
22 BRS	9855	324/73.1,538,548,754,755,756,759,761,765.ccls.	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 14:23		

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
23	BRS	3	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and cell\$1 with pad\$1 with (distance\$1 or space\$1) with temperature\$1	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 14:53		
24	BRS	5	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and cell\$1 with (bond\$1 or pad\$1) with (distance\$1 or space\$1) with temperature\$1	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 14:53		
25	BRS	31	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) with test\$3 and pad\$1 with (space\$2 or distance\$1) with temperature\$1	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 15:21		
26	BRS	0	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) with test\$3 and pad\$1 with (space\$2 or distance\$1) with temperature\$1 with (memory or stor\$3 or sav\$3)	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 15:22		

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
27	BRS	9	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) with test\$3 and pad\$1 with (space\$2 or distance\$1) with temperature\$1 and (memory or stor\$3 or sav\$3)	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	15:24		
28	BRS	6	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and pad\$1 with (space\$2 or distance\$1) with temperature\$1 with (memory or stor\$3 or sav\$3)	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	16:12		
29	BRS	0	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and pad\$1 with (space\$2 or distance\$1) with temperature\$1 with (predetermin\$3 or preset\$4 or reference\$1 or expected) with value\$1	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	16:13		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
30 BRS	9	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and pad\$1 with (space\$2 or distance\$1) with temperature\$1 with (predetermin\$3 or preset\$4 or reference\$1 or expected)	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; 16:13 IBM_TDB			
31 BRS	197	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and pad\$1 with (space\$2 or distance\$1) with temperature\$1	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; 16:43 IBM_TDB			
32 BRS	2	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and pad\$1 with (space\$2 or distance\$1) with temperature\$1 and interface with (user\$1 or operator\$1)	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; 16:25 IBM_TDB			
33 BRS	210	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and pad\$1 with (spac\$3 or distance\$1) with temperature\$1	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; 16:51 IBM_TDB			

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
34 BRS	38	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and bond\$3 with pad\$1 with (spac\$3 or distance\$1) with temperature\$1	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 16:52		
35 BRS	0	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and bond\$3 with pad\$1 with (spac\$3 or distance\$1) with temperature\$1 with (memory or stor\$3 or sav\$3)	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 16:52		
36 BRS	0	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and bond\$3 with pad\$1 with (spac\$3 or distance\$1) with temperature\$1 and value\$1 with (memory or stor\$3 or sav\$3)	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 16:53		
37 BRS	2	((ingegrated adj1 circuit\$1) or ic\$1 or semiconductor\$1 or wafer\$1) and bond\$3 with pad\$1 with (spac\$3 or distance\$1) with temperature\$1 and (memory or stor\$3 or sav\$3)	USPAT; US-PGPUB; EPO; 2004/04/01 JPO; DERWENT; IBM_TDB	2004/04/01 16:53		